MH188 Hall-effect sensor is a temperature stable, stress-resistant sensor. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. This method reduces the offset voltage normally caused by device over molding, temperature dependencies, and thermal stress.

MH188 includes the following on a single silicon chip: voltage regulator, Hall voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, Advanced DMOS wafer fabrication processing is used to take advantage of low-voltage requirements, component matching, very low input-offset errors, and small component geometries.

This device requires the presence of both south and north polarity magnetic fields for operation. In the presence of a south polarity field of sufficient strength, the device output sensor on, and only switches off when a north polarity field of sufficient strength is present.

MH188 is rated for operation between the ambient temperatures -40℃and 85℃ for the E temperature range, and -40℃to 125℃ for the K temperature range. The two package styles available provide magnetically optimized solutions for most applications. Package SO is an SOT-23, a miniature low-profile surface-mount package, while package UA is a three-lead ultra mini SIP for through-hole mounting.

Packages is Halogen Free standard and which have been verified by third party lab.

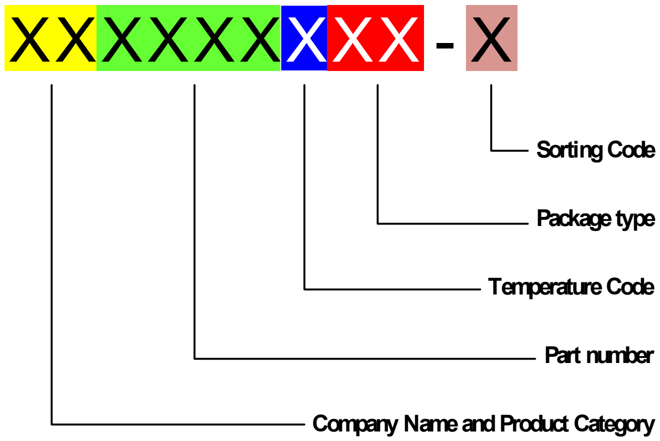
Features and Benefits

- DMOS Hall IC Technology.
- Reverse bias protection on power supply pin.
- Chopper stabilized amplifier stage.
- Optimized for BLDC motor applications.
- Reliable and low shifting on high Temp condition.
- Switching offset compensation at typically 69 kHz.
- Good ESD Protection.
- 100% tested at 125 ℃ for K.
- Custom sensitivity / Temperature selection are available.

Applications

- High temperature Fan motor
- 3 phase BLDC motor application
- Speed sensing
- Position sensing
- Current sensing
- Revolution counting
- Solid-State Switch
- Linear Position Detection
- Angular Position Detection
- Proximity Detection
- High ESD Capability

Ordering Information



Company Name and Product Category

MH:MST Hall Effect/MP:MST Power IC

Part number

181,182,183,184,185,248,249,276,477,381,381F,381R,382…..

If part # is just 3 digits, the forth digit will be omitted.

Temperature range

E: 85 ℃, I: 105 ℃, K: 125 ℃, L: 150 ℃

Package type

UA:TO-92S,VK:TO-92S(4pin),VF:TO-92S(5pin),SO:SOT-23,

SQ:QFN-3,ST:TSOT-23,SN:SOT-553,SF:SOT-89(5pin),

SS:TSOT-26,SD:DFN-6

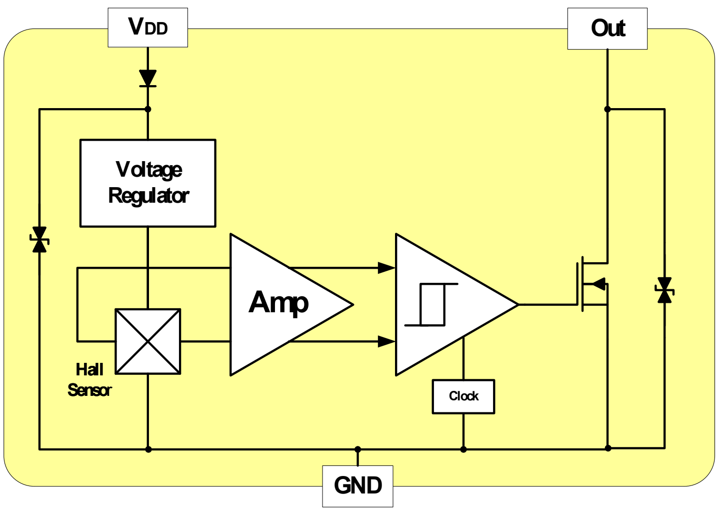
Sorting

α,β,Blank…..

Part No.	Temperature Suffix	Package Type
MH188KUA	K (-40℃ to + 125℃)	UA (TO-92S)
MH188KSO	K (-40℃ to + 125℃)	SO (SOT-23)
MH188EUA	E (-40℃ to + 85℃)	UA (TO-92S)
MH188ESO	E (-40℃ to + 85℃)	SO (SOT-23)

KUA spec is using in industrial and automotive application. Special Hot Testing is utilized.

Functional Diagram



Absolute Maximum Ratings *At (Ta=25℃)*

Characteristics		Values	Unit
Supply voltage, (V_{DD})		28	V
Output Voltage,(V_{out})		28	V
Reverse voltage, (V_{DD})		-28/-0.3	V
Output current, (I_{SINK})		50	mA
Operating Temperature Range, (Ta)	"E" version	-40 to +85	℃
	"K" version	-40 to +125	℃
Storage temperature range, (Ts)		-65 to +150	℃
Maximum Junction Temp,(Tj)		150	℃
Thermal Resistance	(θ_{ja}) UA / SO	206 / 543	℃/W
	(θ_{jc}) UA / SO	148 / 410	℃/W
Package Power Dissipation, (P_D) UA / SO		606 / 230	mW

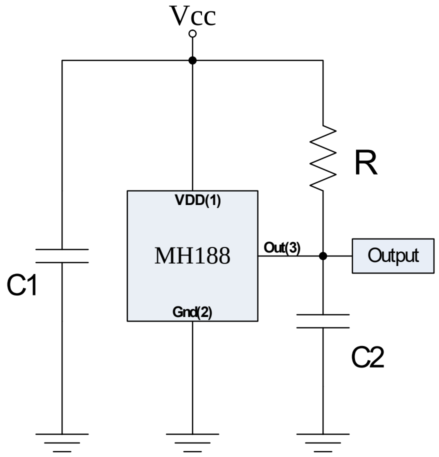
Note*: Do not apply reverse voltage to* V_{DD} *and* V_{OUT} *Pin, It may be caused for Miss function or damaged device.*

Electrical Specifications

DC Operating Parameters ： T_A=+25℃, V_{DD}=12V

Parameters	Test Conditions	Min	Typ	Max	Units
Supply Voltage,(V_{DD})	Operating	2.5		26.0	V
Supply Current,(I_{DD})	B<B_{OP}			5.0	mA
Output Saturation Voltage, (V_{sat})	I_{OUT} = 20 mA, B>B_{OP}			400.0	mV
Output Leakage Current, (I_{off})	I_{OFF} B<B_{RP}, V_{OUT} = 12V			10.0	uA
Internal Oscillator Chopper Frequency,(f_{OSC})			69		kHz
Output Rise Time, (T_R)	R_L=1.1KΩ, C_L =20pF		0.04	0.45	uS
Output Fall Time, (T_F)	R_L=820Ω; C_L =20pF		0.18	0.45	uS
Electro-Static Discharge	HMB	4			KV

Typical application circuit



R：1KΩ

C1：10nF

C2：1nF

MH188 Magnetic Specifications

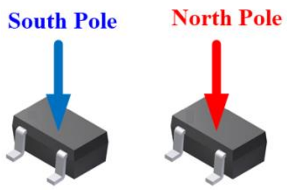
DC Operating Parameters ： T_A=+25℃, V_{DD}=12V

Parameter	Symbol	Test condition	Min	Typ	Max	Unit
Operate Point	B_{OP}	UA(SO)	5(-25)		25(-5)	Gauss
Release Point	B_{RP}	UA(SO)	-25 (5)		-5 (25)	Gauss
Hysteresis	B_{HYS}			30		Gauss

Output Behavior versus Magnetic Pole

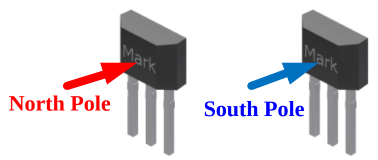
DC Operating Parameters ：Ta = -40 to 125℃, V_{DD} = 2.5 to 26V

Parameter	Test condition	UA OUT	SO OUT
North pole	B>B_{OP}	Open(Pull-up voltage)	Low(V_{DSON})
South pole	B<B_{RP}	Low(V_{DSON})	Open(Pull-up voltage)



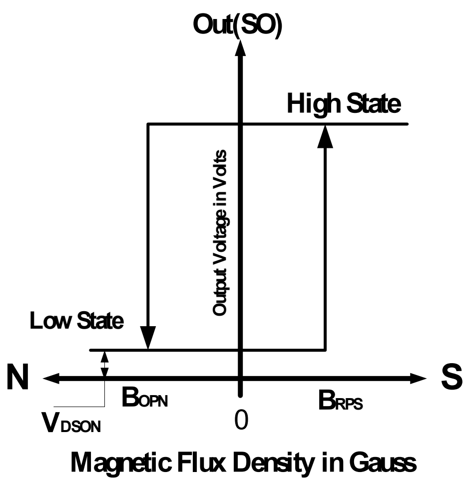
OUT=Hi (Pull-up Voltage) OUT=Low (V_{DSON})

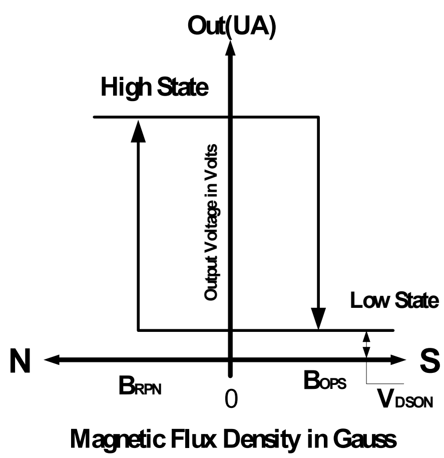
SO package



OUT=Hi (Pull-up Voltage) OUT=Low (V_{DSON})

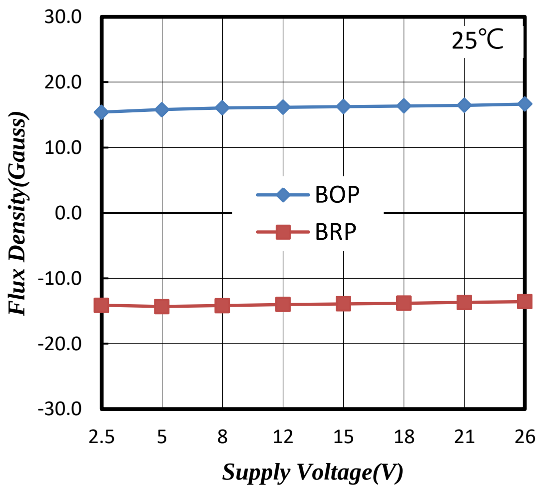
UA package



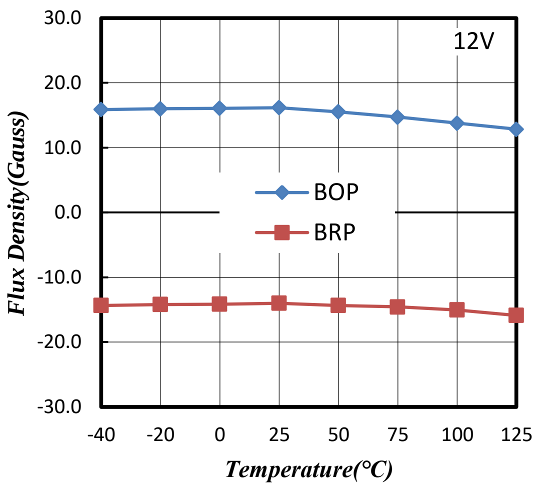


Performance Graph

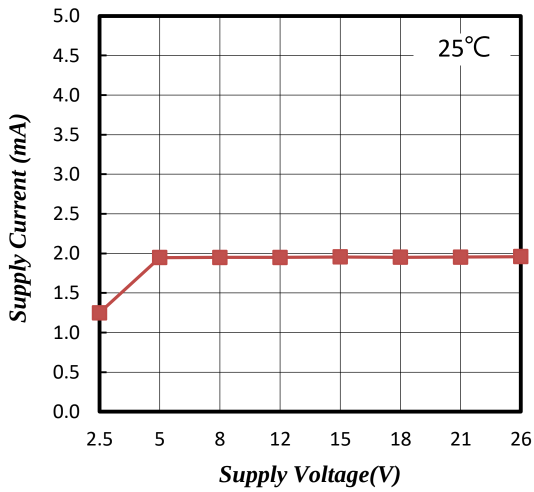
Typical Supply Voltage(V_{DD}) Versus Flux Density



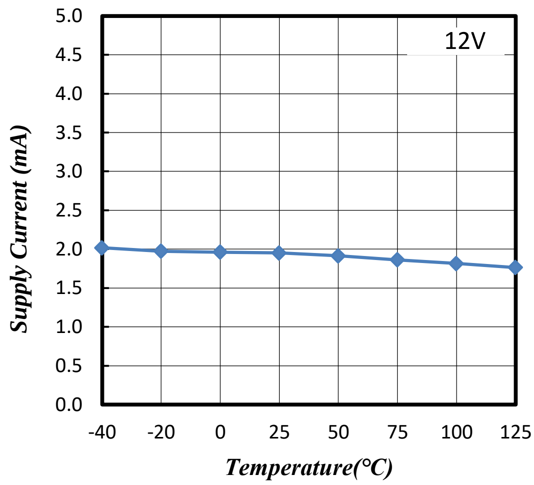
Typical Temperature(T_A) Versus Flux Density



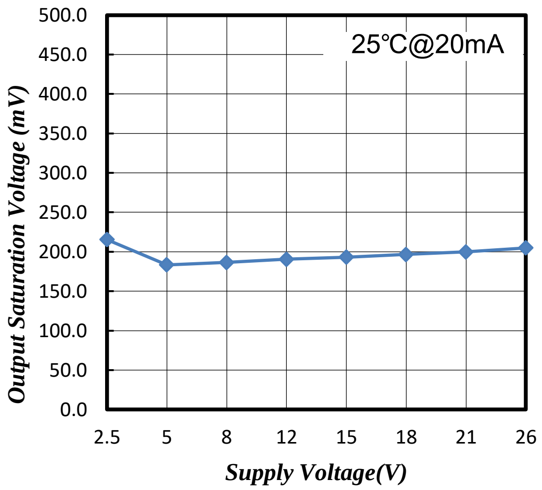
Typical Supply Voltage(V_{DD}) Versus Supply Current(I_{DD})



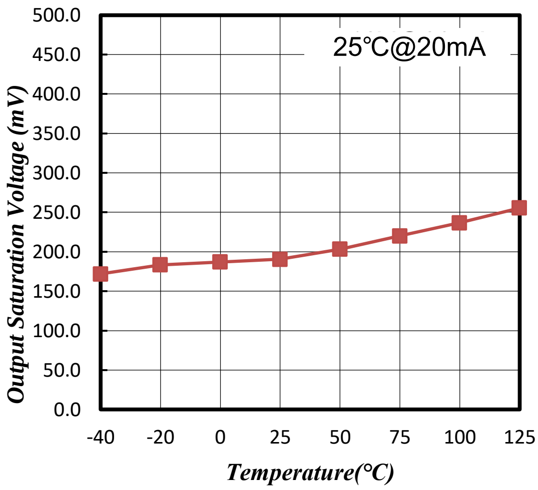
Typical Temperature(T_A) Versus Supply Current(I_{DD})



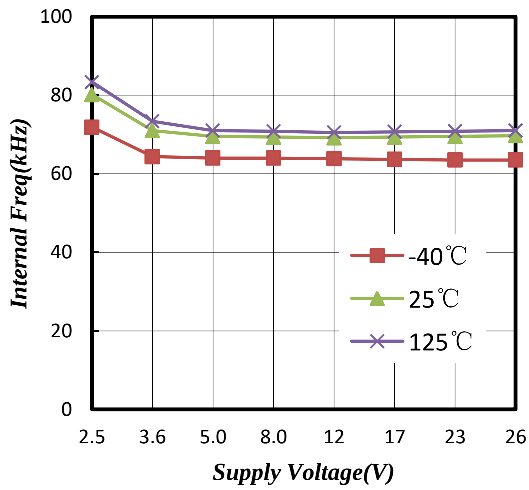
Typical Supply Voltage(V_{DD}) Versus Output Voltage(V_{DSON})



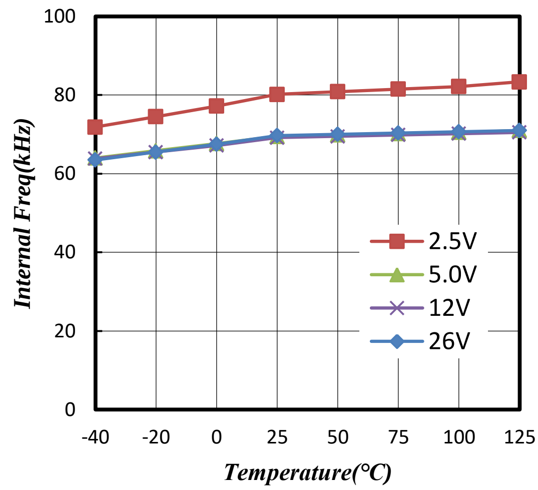
Typical Temperature(T_A) Versus Output Voltage(V_{DSON})



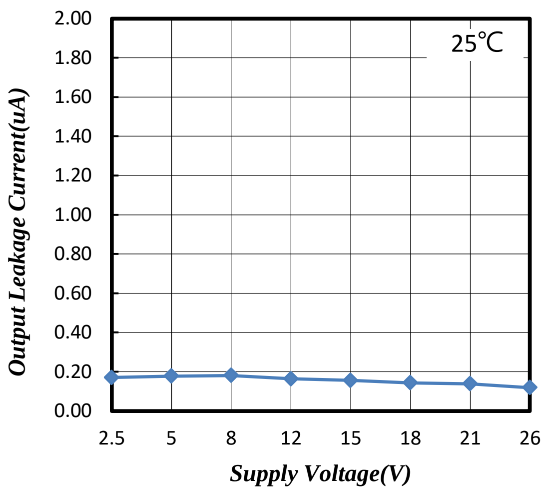
Typical Supply Voltage(V_{DD}) Versus Internal Freq(fosc)



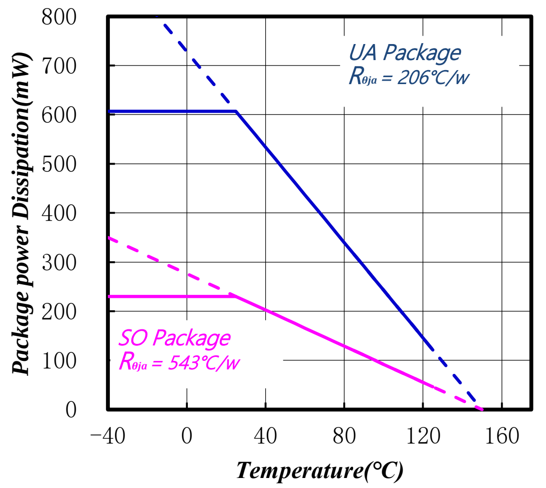
Typical Temperature(T_A) Versus Internal Freq(fosc)



Typical Supply Voltage(V_{DD}) Versus Leakage Current(I_{OFF})



Power Dissipation versus Temperature(T_A)



Package Power Dissipation

The power dissipation of the Package is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, Ta. Using the values provided on the data sheet for the package, PD can be calculated as follows:

$$P_D = \frac{T_{J(max)} - Ta}{R_{\theta ja}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature Ta of 25℃, one can calculate the power dissipation of the device which in this case is 606 milliwatts.

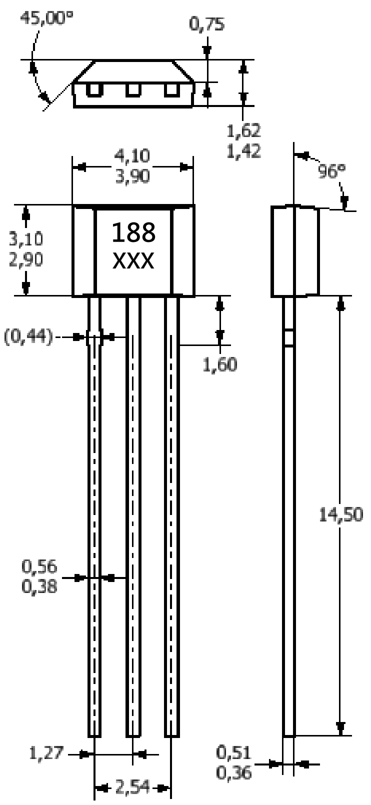
$$P_D(UA) = \frac{150°C - 25°C}{206°C/_W} = 606mW$$

The 206℃/W for the UA package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 606 milliwatts. There are other alternatives to achieving higher power dissipation from the Package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

Sensor Location, Package Dimension and Marking

MH188 Package

UA Package



NOTES:

1).Controlling dimension: mm

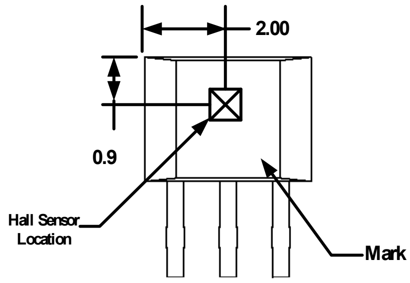
2).Leads must be free of flash and plating voids

3).Do not bend leads within 1 mm of lead to package interface.

4).PINOUT:

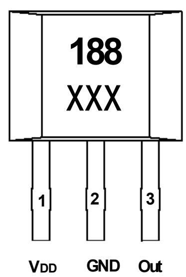
Pin 1	VDD
Pin 2	GND
Pin 3	Output

Hall Chip location

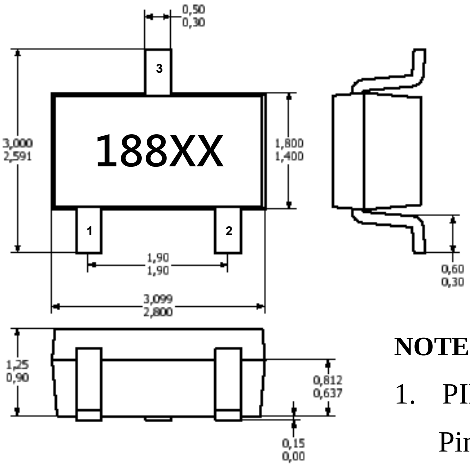


Output Pin Assignment

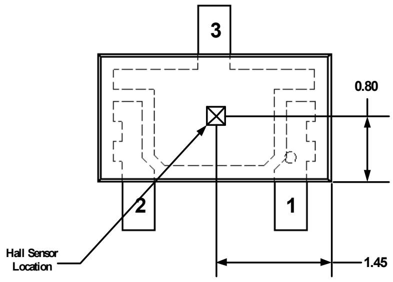
(Top view)



SO Package
(Top View)



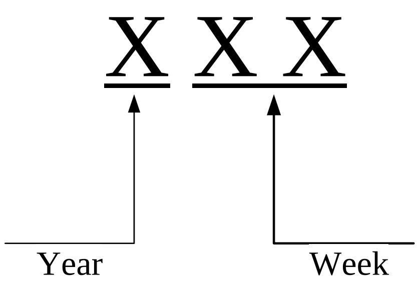
Hall Plate Chip Location
(Bottom view)



NOTES:

1. PIN OUT (See Top View at left :)
   Pin 1 V_{DD}
   Pin 2 Output
   Pin 3 GND
2. Controlling dimension: mm
3. Lead thickness after solder plating will be 0.254mm maximum

MH188 UA(TO-92S) Package Date Code



EX：2016 Year_8 Week → 608

MH188 SO(SOT-23) Package Date Code

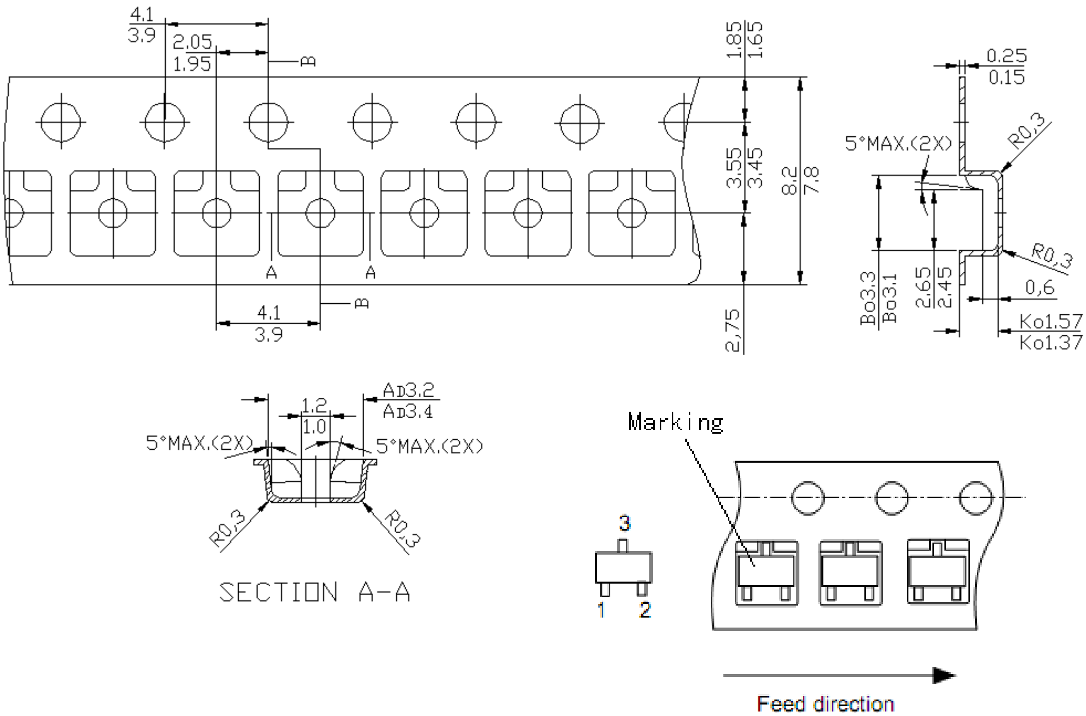
X X

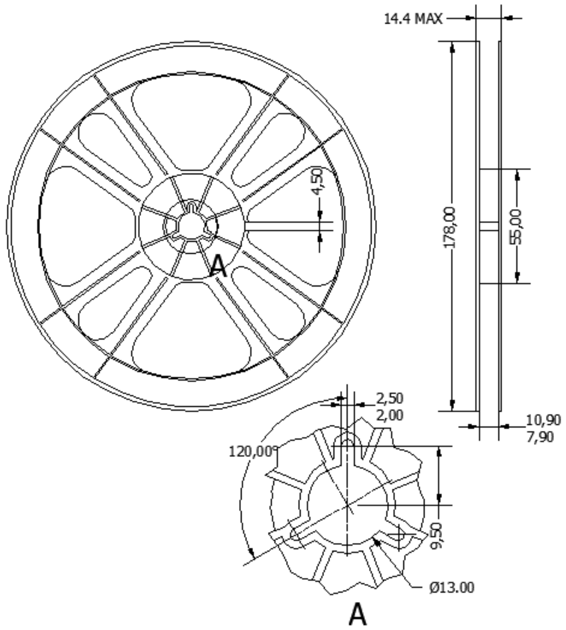
Week Code

week	1	2	3	4	5	6	7	8	9	10	11	12	13
code	WA	WB	WC	WD	WE	WF	WG	WH	WI	WJ	WK	WL	WM
week	14	15	16	17	18	19	20	21	22	23	24	25	26
code	WN	WO	WP	WQ	WR	WS	WT	WU	WV	WW	WX	WY	WZ
week	27	28	29	30	31	32	33	34	35	36	37	38	39
code	XA	XB	XC	XD	XE	XF	XG	XH	XI	XJ	XK	XL	XM
week	40	41	42	43	44	45	46	47	48	49	50	51	52
code	XN	XO	XP	XQ	XR	XS	XT	XU	XV	XW	XX	XY	XZ

EX：2016 Year_8 Week → WH

Sot-23 package Tape On Reel Dimension

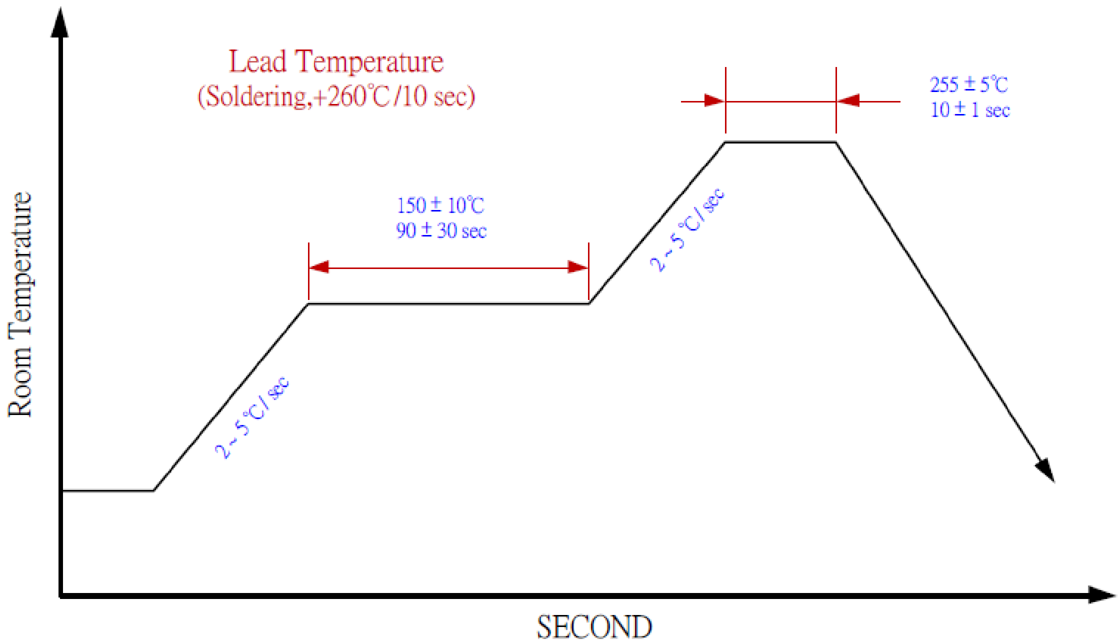




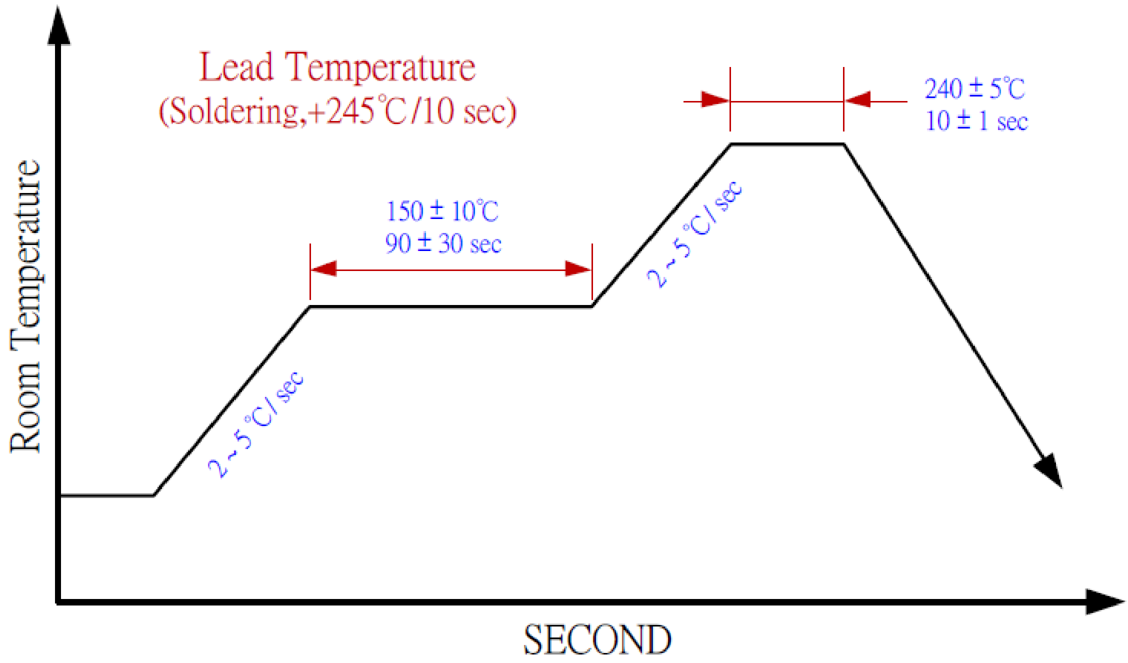
NOTES:

1. Material: Conductive polystyrene;
2. DIM in mm;
3. 10 sprocket hole pitch cumulative tolerance ±0.2;
4. Camber not to exceed 1mm in 100mm;
5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole;
6. (S.R. OHM/SQ) Means surface electric resistivity of the carrier tape.

IR reflow curve



SO Soldering Condition



UA Soldering Condition

Packing specification:

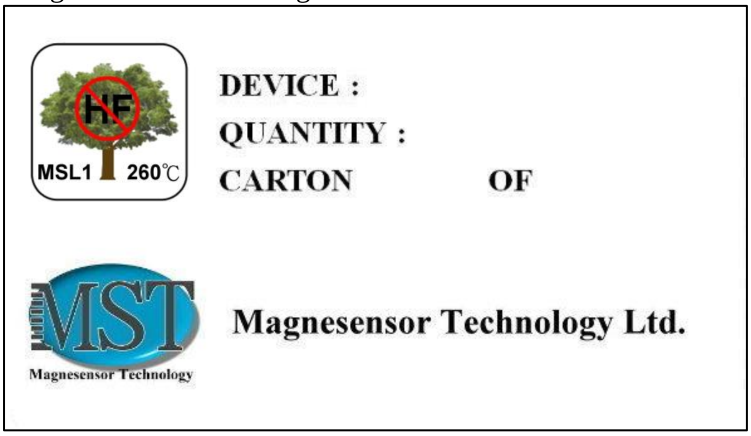
Package	Bag	Box	Carton
TO-92S-3L	1,000pcs / bag	10 bag / box	10 box / carton
SOT-23-3L	3,000pcs / reel	10 reel / box	2 Box / carton

TO-92S-3L	Weight	SOT-23-3L	Weight
1000pcs / bag	0.11kg	3000pcs / reel	0.18kg
10 bags / box	1.24kg	10 reels / box	1.99kg
10 boxes / carton	12.57kg	2 boxes / carton	4.9kg

SOT/TSOT Package Inner box label ***:*** Size: 3.4cm*6.4cm

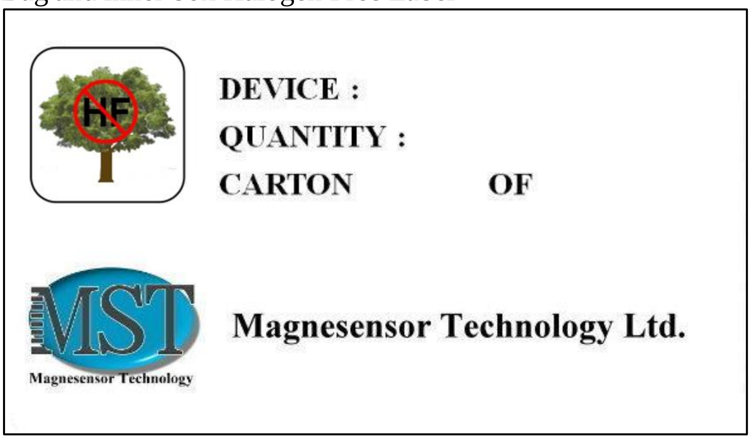
Bag and inner box Halogen Free Label

SOT/TSOT Carton label **：** Size: 5.6 cm * 9.8 cm
Bag and inner box Halogen Free Label



UA Package Inner box label **：** Size: 3.4cm*6.4cm
Bag and inner box Halogen Free Label

UA Carton label **：** Size: 5.6 cm * 9.8 cm
Bag and inner box Halogen Free Label



Combine:

When combine lot, one reel could have two D/C and no more than two DC. One carton could have two devices, no more than two;